Low-Power Voltage Output Temperature Sensor

Features

- · Tiny Analog Temperature Sensor
- Available Packages: SC70-5
- Wide Temperature Measurement Range:
 - -40°C to +125°C
- Accuracy: ±4°C (max.), 0°C to +70°C
- Optimized for Analog-to-Digital Converters (ADCs):

- MCP9700: 10.0 mV/°C (typ.)

- MCP9701: 19.5 mV/°C (typ.)

Wide Operating Voltage Range:

- MCP9700: $V_{DD} = 2.3V$ to 5.5V

- MCP9701: $V_{DD} = 3.1V$ to 5.5V

Low Operating Current: 6 μA (typ.)

· Optimized to Drive Large Capacitive Loads

Typical Applications

- · Hard Disk Drives and Other PC Peripherals
- · Entertainment Systems
- · Home Appliance
- Office Equipment
- Battery Packs and Portable Equipment
- General Purpose Temperature Monitoring

Description

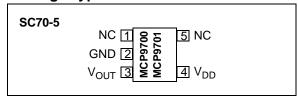
The MCP9700/01 low-cost, low-power and tiny temperature sensor family converts temperature to an analog voltage. It provides an accuracy of $\pm 4^{\circ}\text{C}$ from 0°C to $+70^{\circ}\text{C}$ while consuming 6 μA (typ.) of operating current

The MCP9700/01 provides a low-cost solution for applications that require measurement of a relative change of temperature. When measuring relative change in temperature from 25°C, an accuracy of ± 1 °C (typ.) can be realized from 0°C to 70°C. This accuracy can also be achieved by applying system calibration at 25°C.

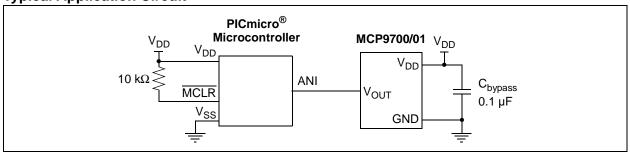
Unlike resistive sensors such as thermistors, this family does not require a signal conditioning circuit. The voltage output pin can be directly connected to an ADC input of a microcontroller. The MCP9700 and MCP9701 temperature coefficients are scaled to provide a 1° C/bit resolution for an 8-bit ADC with a reference voltage of 2.5V and 5V, respectively.

In addition, this family is immune to the effects of parasitic capacitance and can drive large capacitive loads. This provides Printed Circuit Board (PCB) layout design flexibility by enabling the device to be remotely located from the microcontroller. Adding some capacitance at the output also helps the output transient response by reducing overshoots or undershoots. However, capacitive load is not required for sensor output stability.

Package Type



Typical Application Circuit



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

V _{DD} :	6.0V
Storage temperature:65°C	C to +150°C
Ambient Temp. with Power Applied:40°C	C to +125°C
Junction Temperature (T _J):	150°C
ESD Protection On All Pins: (HBM:MM):	(4 kV:200V)
Latch-Up Current at Each Pin:	+200 mA

†Notice: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Pin Function

NAME	FUNCTION				
NC	Not Connected				
V _{OUT}	Voltage Output				
V_{DD}	Power Supply				
GND	Ground				

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated:

MCP9700: V_{DD} = 2.3V to 5.5V, GND = Ground, T_A = -40°C to +125°C and No load. **MCP9701:** V_{DD} = 3.1V to 5.5V, GND = Ground, T_A = -10°C to +125°C and No load.

Parameter	Sym	Min	Тур	Max	Unit	Conditions
Power Supply				•		<u> </u>
Operating Voltage Range	V _{DD} V _{DD}	2.3 3.1	_	5.5 5.5	V V	MCP9700 MCP9701
Operating Current	I _{DD}	_	6	12	μA	
Power Supply Rejection	PSR	_	0.1	_	°C/V	MCP9700 $V_{DD} = 2.3V - 4.0V$ MCP9701 $V_{DD} = 3.1V - 4.0V$
Sensor Accuracy (Notes 1, 2)						
$T_A = +25$ °C $T_A = 0$ °C to +70°C $T_A = -40$ °C to +125°C $T_A = -10$ °C to +125°C	T _{ACY} T _{ACY} T _{ACY} T _{ACY}	-4.0 -4.0 -4.0	±1 — —	+4.0 +6.0 +6.0	္ပံ ဂိဂိဂိ	MCP9700 MCP9701
Sensor Output						
Output Voltage: T _A = 0°C T _A = 0°C	V _{0°C}	_	500 400	_	mV mV	MCP9700 MCP9701
Temperature Coefficient	T _{C1} T _{C1}		10.0 19.5	_	mV/°C mV/°C	MCP9700 MCP9701
Output Non-linearity	V _{ONL}	_	±0.5	_	°C	$T_A = 0$ °C to +70°C (Note 2)
Output Current	I _{OUT}		_	100	μA	
Output Impedance	Z _{OUT}		20	_	Ω	$I_{OUT} = 100 \mu A, f = 500 Hz$
Output Load Regulation	ΔV _{OUT} / ΔI _{OUT}	l	1	_	Ω	$T_A = 0$ °C to +70°C, $I_{OUT} = 100 \mu A$
Turn-on Time	t _{ON}		800	_	μs	
Typical Load Capacitance (Note 3)	C _{LOAD}		_	1000	pF	
Thermal Response to 63%	t _{RES}	_	1.3	_	S	30°C (air) to +125°C (fluid bath) (Note 4)

Note 1: The MCP9700 accuracy is tested with $V_{DD} = 3.3V$, while the MCP9701 accuracy is tested with $V_{DD} = 5.0V$.

- 2: The MCP9700/01 is characterized using the first-order or linear equation, as shown in Equation 3-1.
- 3: The MCP9700/01 family is characterized and production-tested with a capacitive load of 1000 pF.
- 4: Thermal response with 1 x 1 inch dual-sided copper clad.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated,

MCP9700: $V_{DD} = 2.3V$ to 5.5V, GND = Ground, $T_A = -40$ °C to +125°C and No load. **MCP9701:** $V_{DD} = 3.1V$ to 5.5V, GND = Ground, $T_A = -10$ °C to +125°C and No load.

Parameters	Sym	Min	Тур	Max	Units	Conditions	
Temperature Ranges							
Specified Temperature Range	T _A	-40	_	+125	°C	MCP9700 (Note 1)	
	T _A	-10	_	+125	°C	MCP9701 (Note 1)	
Operating Temperature Range	T _A	-40	_	+125	°C		
Storage Temperature Range	T _A	-65	_	+150	°C		
Thermal Package Resistances							
Thermal Resistance, 5L-SC70	θ_{JA}	_	331	-	°C/W		

Note 1: Operation in this range must not cause T_J to exceed Maximum Junction Temperature (+150°C).

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

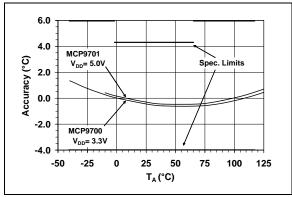


FIGURE 2-1: Accuracy vs. Ambient Temperature.

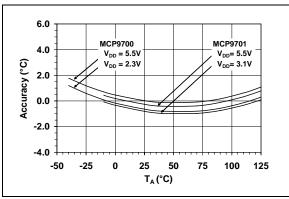


FIGURE 2-2: Accuracy vs. Ambient Temperature, with V_{DD} .

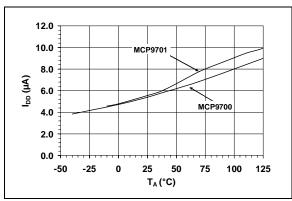


FIGURE 2-3: Supply Current vs. Temperature.

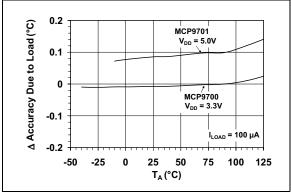


FIGURE 2-4: Changes in Accuracy vs. Ambient Temperature (Due to Load).

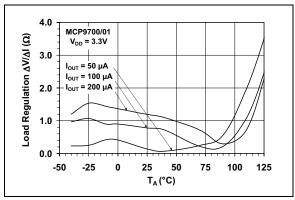


FIGURE 2-5: Load Regulation vs. Ambient Temperature.

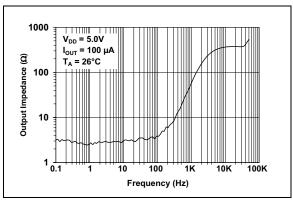


FIGURE 2-6: Output Impedance vs. Frequency.

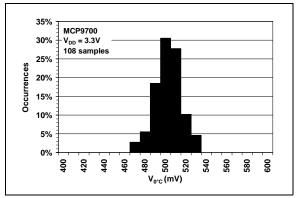


FIGURE 2-7: Output Voltage at 0°C (MCP9700).

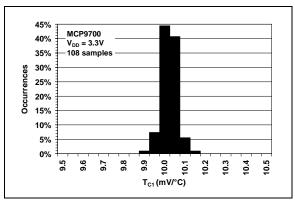


FIGURE 2-8: Occurrences vs. First-Order Temperature Coefficient (MCP9700).

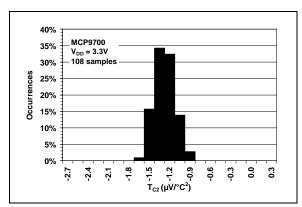


FIGURE 2-9: Occurrences vs. Second-Order Temperature Coefficient (MCP9700).

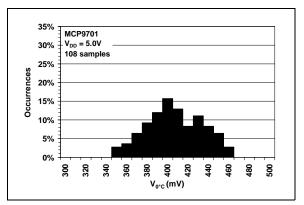


FIGURE 2-10: Occurrences vs. Temperature Coefficient (MCP9701).

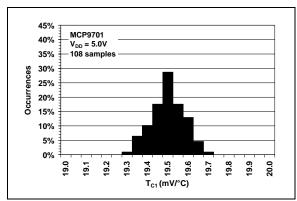


FIGURE 2-11: Occurrences vs. First-Order Temperature Coefficient (MCP9701).

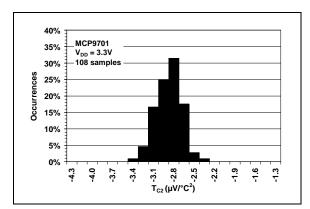


FIGURE 2-12: Occurrences vs. Second-Order Temperature Coefficient (MCP9701).

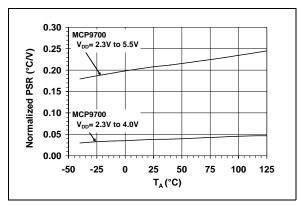


FIGURE 2-13: Power Supply Rejection (PSR) vs. Ambient Temperature.

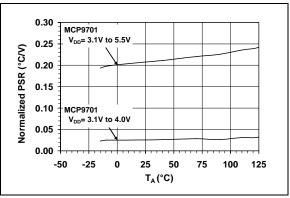


FIGURE 2-14: Power Supply Rejection (PSR) vs. Frequency.

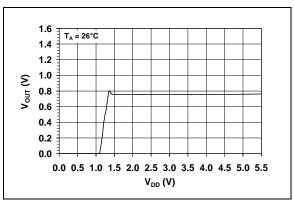


FIGURE 2-15: Output Voltage vs. Power Supply.

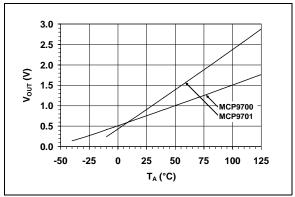


FIGURE 2-16: Output Voltage vs. Ambient Temperature.

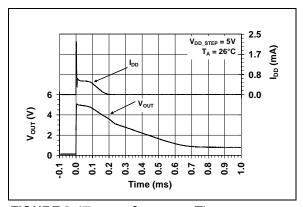


FIGURE 2-17: Output vs. Time.

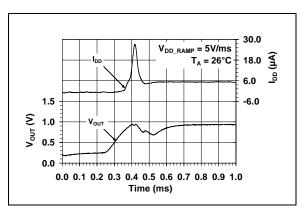


FIGURE 2-18: Output vs. Time

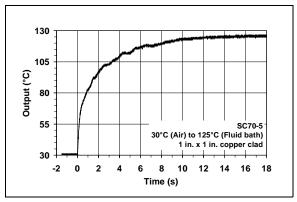


FIGURE 2-19: Thermal Response.

3.0 FUNCTIONAL DESCRIPTION

The MCP9700/01 temperature sensing element is essentially a P-N junction or a diode. The diode electrical characteristics has a temperature coefficient that provides a change in voltage based on the relative ambient temperature from -40°C to 125°C. The change in voltage is scaled to a temperature coefficient of 10.0 mV/°C (typ.) for the MCP9700 and 19.5 mV/°C (typ.) for the MCP9701. The output voltage at 0°C is also scaled to 500 mV (typ.) and 400 mV (typ.) for the MCP9700 and MCP9701, respectively. This linear scale is described in the transfer function shown in Equation 3-1.

EQUATION 3-1: SENSOR TRANSFER FUNCTION

 $V_{OUT} = T_{C1} \bullet T_A + V_{0^{\circ}C}$

Where:

 T_A = Ambient Temperature

 V_{OUT} = Sensor Output Voltage

 $V_{0^{\circ}C}$ = Sensor Output Voltage at $0^{\circ}C$

T_{C1} = Temperature Coefficient

4.0 APPLICATIONS INFORMATION

4.1 Improving Accuracy

The MCP9700/01 accuracy can be improved by performing a system calibration at a specific temperature. For example, calibrating the system at 25°C ambient improves the measurement accuracy to a ± 0.5 °C (typ.) from 0°C to 70°C, as shown in Figure 4-1. Therefore, when measuring relative temperature change, this family measures temperature with higher accuracy.

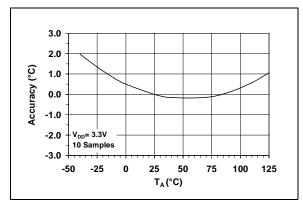


FIGURE 4-1: Relative Accuracy to +25°C vs. Temperature.

The relative change in accuracy from the calibration temperature is due to the output non-linearity from the first-order equation, specified in Equation 3-1. The accuracy can be further improved by compensating for the output non-linearity.

For higher accuracy, the sensor output transfer function is also derived using a second-order equation as shown in Equation 4-1. The equation describes the output non-linearity. This equation is not used to characterize the part as specified in the DC Electrical Characteristics table; however, it provides better accuracy.

EQUATION 4-1: SECOND-ORDER TRANSFER FUNCTION

$$\begin{split} V_{OUT} &= T_{C2} \ (T_A + 10^{\circ}\text{C}) (125^{\circ}\text{C} - T_A) + T_{C1} \ T_A + V_{0^{\circ}\text{C}} \\ &= -T_{C2} \ T_A^2 + (T_{C1} + 115 \ T_{C2}) T_A + 1250 \ T_{C2} + V_{0^{\circ}\text{C}} \\ \end{split}$$
 Where:
$$\begin{split} T_A &= \text{Ambient Temperature} \\ V_{OUT} &= \text{Sensor Output Voltage} \\ V_{0^{\circ}\text{C}} &= \text{Sensor Output Voltage at 0°C} \\ &\text{(refer to Figure 2-7 and 2-10)} \\ T_{C1} &= \text{Temperature Coefficient} \\ &\text{(refer to Figure 2-8 and 2-11)} \\ T_{C2} &= \text{Temperature Coefficient} \\ &\text{MCP9700 1.4 } \mu\text{V/°C}^2 \ (\text{typ.)} \\ &\text{MCP9701 2.7 } \mu\text{V/°C}^2 \ (\text{typ.)} \\ &\text{(refer to Figure 2-9 and 2-12)} \end{split}$$

4.2 Shutdown Using Microcontroller I/O Pin

The MCP9700/01 low operating current of 6 μ A (typ.) makes it ideal for battery-powered applications. However, for applications that require tighter current budget, this device can be powered using a microcontroller Input/Output (I/O) pin. The I/O pin can be toggled to shutdown the device. In such applications, the microcontroller internal digital switching noise is emitted to the MCP9700/01 as power supply noise. This switching noise compromises measurement accuracy. Therefore, a decoupling capacitor will be necessary.

4.3 Layout Considerations

The MCP9700/01 does not require any additional components to operate. However, it is recommended that a decoupling capacitor of 0.1 μF to 1 μF be used between the V_{DD} and GND pins. In high-noise applications, connect the power supply voltage to the V_{DD} pin using a 200Ω resistor with a 1 μF decoupling capacitor. A high-frequency ceramic capacitor is recommended. It is necessary for the capacitor to be located as close as possible to the V_{DD} and GND pins in order to provide effective noise protection. In addition, avoid tracing digital lines in close proximity to the sensor.

4.4 Thermal Considerations

The MCP9700/01 measures temperature by monitoring the voltage of a diode located in the die. A low impedance thermal path between the die and the PCB is provided by the pins. Therefore, the MCP9700/01 effectively monitors the temperature of the PCB. However, the thermal path for the ambient air is not as efficient because the plastic device package functions as a thermal insulator from the die. This limitation applies to plastic-packaged silicon temperature sensors. If the application requires measuring ambient air, the PCB needs to be designed with proper thermal conduction to the sensor pins.

The MCP9700/01 is designed to source/sink 100 μ A (max.). The power dissipation due to the output current is relatively insignificant. The effect of the output current can be described using Equation 4-2.

EQUATION 4-2: EFFECT OF SELF-HEATING

 $T_J - T_A = \theta_{JA}(V_{DD}I_{DD} + (V_{DD} - V_{OUT})I_{OUT})$

Where:

 T_J = Junction Temperature T_A = Ambient Temperature

 θ_{JA} = Package Thermal Resistance (331°C/W)

V_{OUT} = Sensor Output Voltage

I_{OUT} = Sensor Output Current I_{DD} = Operating Current

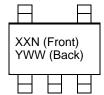
 V_{DD} = Operating Current

At T_A = +25°C (V_{OUT} = 0.75V) and maximum specification of I_{DD} = 12 μ A, V_{DD} = 5.5V and I_{OUT} = +100 μ A, the self-heating due to power dissipation ($T_J - T_A$) is 0.179°C.

5.0 PACKAGING INFORMATION

5.1 Package Marking Information

5-Lead SC-70 (MCP9700)



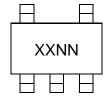
Device	Code			
MCP9700	AUN			
MCP9701	AVN			
N 4 A 1 4 5 1 100 70				

Example:

AU2 (Front)
548 (Back)

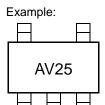
Note: Applies to 5-Lead SC-70.

5-Lead SC-70 (MCP9701)



Device	Code
MCP9700	AUNN
MCP9701	AVNN

Note: Applies to 5-Lead SC-70.



Legend: XX...X Customer-specific information
Year code (last digit of calendary)

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

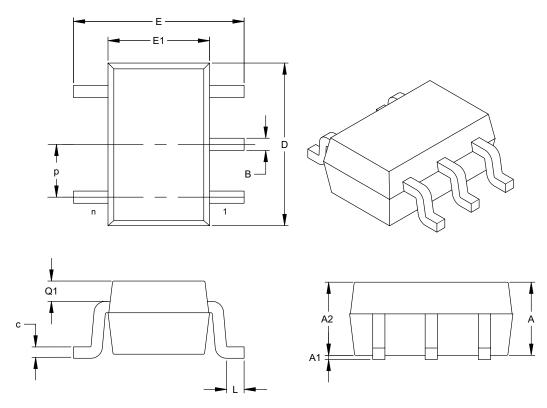
e3 Pb-free JEDEC designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (e3)

can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

5-Lead Plastic Small Outline Transistor (LT) (SC-70)



	Units	INCHES			MILLIMETERS*		
Dimension	MIN	NOM	MAX	MIN	NOM	MAX	
Number of Pins	n	5			5		
Pitch	р	.026 (BSC)			0.65 (BSC)		
Overall Height	Α	.031		.043	0.80		1.10
Molded Package Thickness	A2	.031		.039	0.80		1.00
Standoff	A1	.000		.004	0.00		0.10
Overall Width	E	.071		.094	1.80		2.40
Molded Package Width	E1	.045		.053	1.15		1.35
Overall Length	D	.071		.087	1.80		2.20
Foot Length	L	.004		.012	0.10		0.30
Top of Molded Pkg to Lead Shoulder	Q1	.004		.016	0.10		0.40
Lead Thickness	С	.004		.007	0.10		0.18
Lead Width	В	.006		.012	0.15		0.30

^{*}Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEITA (EIAJ) Standard: SC-70 Drawing No. C04-061

APPENDIX A: REVISION HISTORY

Revision A (March 2005)

• Original Release of this Document.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	- <u>X</u> /XX		Examples:			
Device	Temperature Package Range	a)	MCP9700T-E/LT:	Tiny Analog Temperature Sensor, Tape and Reel, -40°C to +125°C, 5LD SC70 package.		
Device:	MCP9700T: Tiny Analog Temperature Sensor, Tape and Reel, Pb free MCP9701T: Tiny Analog Temperature Sensor, Tape and Reel, Pb free	a)	MCP9701T-E/LT:	Tiny Analog Temperature Sensor, Tape and Reel, -40°C to +125°C, 5LD SC70 package.		
Temperature Range:	$E = -40^{\circ}C \text{ to } +125^{\circ}C$					
Package:	LT = Plastic Small Outline Transistor, 5-lead					

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